

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**C. Amendments to the Claims.**

1. (Original) A method, comprising the steps of:

5 bending a substrate by applying a force with a movable chuck portion to orient essentially all of a surface of the substrate at a predetermined angle with respect to an input source.

2. (Original) The method of claim 1, wherein:

the substrate comprises a silicon wafer having a diameter of at least about eight inches.

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3. (Original) The method of claim 1, wherein:

the force comprises an electrostatic force generated by a potential difference between the substrate and the movable chuck portion.

15 4. (Original) The method of claim 1, wherein:

the movable portion comprises a split electrode electrostatic chuck.

5. (Original) The method of claim 1, wherein:

bending the substrate includes receiving the substrate in a recess

20 having a concave shape.

6. (Original) The method of claim 5, wherein:

bending the substrate includes introducing a curvature into the substrate selected from the group consisting of spherical, conical and cylindrical.

7. (Original) The method of claim 1, wherein:

applying the force with a movable chuck portion includes attracting the substrate to the movable portion with an electrostatic force when the substrate has an

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essentially unbent shape, and moving the movable chuck portion with respect to a stationary substrate receiving portion.

8. (Original) The method of claim 1, wherein:

5 applying the force with a movable chuck portion includes moving the movable chuck portion with respect to a stationary substrate receiving portion to bend the substrate.

9. (Original) The method of claim 8, further including:

10 attracting the substrate receiving portion to a curved stationary substrate receiving portion with an electrostatic force.

10. (Original) A method of processing a integrated circuit wafer, comprising the steps of:

15 placing a wafer over a concave chuck portion;  
applying a force to the wafer to conform to the concave chuck portion;  
maintaining the wafer in the deformed shaped as the wafer is processed with respect to an input source.

11. (Original) The method of claim 10, wherein:

20 placing the wafer over the concave portion includes attracting the wafer with an electrostatic force to the concave portion.

12. (Currently Amended) The method of claim 11~~12~~, wherein:

25 attracting the wafer includes applying a voltage to an electrostatic chuck within the concave portion.

13. (Original) The method of claim 10, wherein:

30 placing the wafer over the concave portion includes orienting the wafer in a first direction; and  
the force is applied with a movable chuck portion at an angle greater than 45° with respect to the first direction.

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14. (Original) The method of claim 13, wherein:

placing the wafer over the concave portion includes contacting a stationary chuck portion with a first side of the wafer; and  
the force is applied by a movable portion to a second side of the wafer that is opposite to the first side.

15. (Original) The method of claim 13, wherein:

placing the wafer over the concave portion includes contacting a stationary chuck portion with a first side of the wafer; and

the force applied by the movable portion is an electrostatic force that attracts the first side of the wafer to the movable portion.

16. (Original) A system, comprising:

an input source for processing the substrate according to a predetermined manufacturing step;

a chuck system having

a substrate receiving surface that receives the substrate in an essentially non-deformed shape, and

a force applying portion that applies an attractive force between the substrate and the chuck system that maintains the substrate in a deformed shape.

17. (Original) The system of claim 16, wherein:

the input source comprises an ion implantation source.

18. (Original) The system of claim 16, wherein:

25 the substrate receiving surface has a type of curve selected from the group consisting of spherical, conical, and cylindrical.

19. (Original) The system of claim 16, wherein:

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the force applying portion includes a movable portion that moves with respect to the substrate receiving surface to change the substrate from the non-deformed shape to the deformed shape.

20. (Original) The system of claim 19, wherein:

5                   the force applied by the movable portion is selected from the group consisting of electrostatic force and mechanical force.

21. (New) The method of claim 1, wherein:

10                   after bending the substrate, clamping the substrate to a recessed receiving portion to maintain the substrate in a bent state.